nexperia

Final Product Change Notification

201911007F01

Issue Date:31-Dec-2019Effective Date:30-Mar-2020

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Management Summary

Re-layout of die for products assembled in SOT353 package in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

Change Category

[] Wafer Fab Process	[] Assembly	[] Product Marking	[] Test	[X] Design
	Process		Location	
[] Wafer Fab Materials	/	[] Mechanical Specificatio	n[]Test	[] Errata
	Materials		Process	
[] Wafer Fab Location	[] Assembly		[] Test	[] Electrical
	Location	Packing/Shipping/Labeling	Equipment	spec./Test
	_			coverage

Bond-pad relocation for products assembled in SOT353 in ATSN, Malaysia

Details of this Change

Bond-pad relocation for products assembled in SOT353 in ATSN (Nexperia Assembly & Test Plant Seremban Malaysia)

- Created optimized die for SOT353 package

- Improved die aspect ratio and bond-pad relocation to improve intrinsic quality for wire-bond process

- Identical IP used resulting in same performance as existing die

- No change in diffusion fab, assembly location or ordering part number

Why do we Implement this Change

To improve the intrinsic quality

Identification of Affected Products

The changed products can be identified by backward traceability of the product marking date code as well as on the reel and box labels

Product Availability

Sample Information

Samples are available upon request Samples are available upon request from the Logic sample store Nijmegen The Netherlands **Production** Planned first shipment 30-Mar-2020

Impact

No change in form, fit, function, quality or reliability anticipated No change in electrical distribution No change in data sheet and test limits No assembly location change No fab location change **Data Sheet Revision** No impact to existing datasheet **Disposition of Old Products** Existing inventory will be shipped until depleted **Timing and Logistics** Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Jan-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

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Affected Part Numbers

74AUP1G07GW,125	74LVC1G125GW,125
74LVC1G02GW,125	74AUP1G04GW,125
74LVC1G32GW,125	74LVC1GU04GW,125
74AUP1G08GW,125	74AUP1G32GW,125
74AUP1G126GW,125	74LVC1G06GW,125
74LVC1G14GW,125	74LVC1G126GW,125
74LVC1G34GW,125	74AUP1G02GW,125
74LVC1G07GW,125	74LVC1G17GW,125
74LVC1G00GW,125	74LVC1G08GW,125
74AUP1G34GW,125	74LVC1G04GW,125